

Supplier Name: **Texas Instruments Inc. (DUNS# 00-732-1904)**
 Contact Info: ti.com/support
 Form/Declaration Type: **Distribute - RoHS and IEC 62474 DB**
 Created on: **06/14/2022**

Details for "LM2574HVM-15"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
LM2574HVM-15	SNPB	Level-2A-2Z0C-4 WEEK	Texas Instruments Electronics	NPA 14	8.99 x 7.5 x 2.3	373.6

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
No	Affected	Yes	Affected

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.099713	99.993983	999940	0.026688	267
Copper and Its Alloys	Iron	7439-89-6	0.000001	0.001003	10	0	0
Nickel and Its Alloys	Nickel	7440-02-0	0.000001	0.001003	10	0	0
Other Nonferrous Metals and Alloys	Manganese	7439-96-5	0.000001	0.001003	10	0	0
Precious Metals	Silver	7440-22-4	0.000003	0.003008	30	0.000001	0
Sub-Total			0.099719	100	1000000	0.02669	267
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	1.092337	75.000017	750000	0.292363	2924
Thermoplastics	Epoxy	85954-11-6	0.364112	24.999983	250000	0.097454	975
Sub-Total			1.456449	100	1000000	0.389818	3898
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	79.550149	96.850314	968503	21.291546	212915
Copper and Its Alloys	Iron	7439-89-6	1.962883	2.389761	23898	0.525364	5254
Copper and Its Alloys	Phosphorus	7723-14-0	0.024639	0.029997	300	0.006595	66
Precious Metals	Silver	7440-22-4	0.500987	0.609939	6099	0.134089	1341
Zinc and Its Alloys	Zinc	7440-66-6	0.098555	0.119988	1200	0.026378	264
Sub-Total			82.137213	100	1000000	21.983973	219840
Lead Frame Plating							
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.828	15	150000	0.221614	2216
Other Nonferrous Metals and Alloys	Tin	7440-31-5	4.692	85	850000	1.255811	12558
Sub-Total			5.52	100	1000000	1.477424	14774
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	246.11386	89	890000	65.872217	658722
Other Nonferrous Metals and Alloys	Metal Hydroxide	Trade Secret	8.295973	3	30000	2.220412	22204
Thermoplastics	Epoxy	85954-11-6	22.122594	8	80000	5.921098	59211
Sub-Total			276.532427	100	1000000	74.013727	740137
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	7.877353	100	1000000	2.108368	21084
Sub-Total			7.877353	100	1000000	2.108368	21084
Total			373.623161			100	1000000

Important Note
 The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information
 There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSLs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
[For an explanation of the methods used to determine material weights. See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/ecoinfo
 Created on: 06/14/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.